

**Patent**  
Attorney Docket No: RENA-05U1

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: )  
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Franck Delahaye       )  
Application Number: 10/599,208     )  
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Filed: September 22, 2006        )  
                            )  
For: PROCESS FOR THE TREATMENT    )  
OF SUBSTRATE SURFACES        )  
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Examiner: Maki A. Angadi

Art Unit: 1713

Commissioner for Patents  
PO Box 1450  
Alexandria, VA 22313

**Information Disclosure Statement**

Sir:

Applicant provides herewith a listing of references on the attached form PTO-SB08 and a copy of each cited foreign document. Applicant submits this information disclosure statement together with a Request for Continued Examination (RCE) for the above identified application. Accordingly, no fee is deemed necessary.

On the attached form PTO-SB08, Document F1 relates to a silicon wafer which is floated on an etching liquid bath by surface tension, as shown in Fig. 1. The level of the etching liquid portion that contacts with the undersurface of the wafer is lower than the level of the etching liquid portion that does not contact with the undersurface of the water. Fig. 2 shows a plane ring-shaped liquid bath. The specification also indicates that it may be possible to employ a linearly shaped liquid bath. As shown in Figs. 2 and 3, the liquid bath has a rotation shaft (14). Rotation shaft (14) has a large number of arms (15) and, for each of the arms (15), a transfer (16) is provided. By rotating rotation shaft (14), transfer (16) is rotated, and the rotated transfer pushes the side surface of the wafer floated on the liquid bath, whereby the wafer is subject to etching. Additionally, the etching liquid is supplied from a supply opening (5) and is discharged

from a discharging mechanism (6).

Document F2 relates to a washing tank (1) and a liquid tank (2). A bottom portion of washing tank (1) and a bottom portion of liquid tank (2) are communicated by a pipe (3). Pipe (3) is provided with a pump (4), and washing liquid (5) in liquid tank (2) can be pumped up to the bottom portion of washing tank (1). Since washing liquid (5) is continuously pumped up, washing liquid (5) overflows from a sidewall (11) of washing tank (1) and a liquid elevated portion (51) where the liquid surface is higher than the upper end of sidewall (11) of washing tank (1) is formed. Washing liquid (5) overflowing from washing tank (1) is returned to liquid tank (2), whereby circulation of washing liquid (5) is formed. Additionally, a filter may be provided in the circulation path as needed.

Document F3 relates to a device for washing a glass substrate for liquid crystal. As shown in Fig. 1, within an oscillation container (11), washing liquid (L) supplied from a supply tube (14) is filled, and overflows from the upper end of the sidewall of oscillation container (11). An ultrasonic generator (18), an oscillator (17), and an oscillation plate (16) are provided to oscillation container (11). With the ultrasonic vibration caused by these units, waves (w) upwardly lifting washing liquid (L) are generated in a central portion (i.e. halfway in Fig. 1) in a width direction of oscillation container (11). Horizontal conveying means (21) is provided above oscillation container (11); a large plate-shaped object (22) subject to washing that is conveyed by the conveying means comes into contact with washing liquid (L); and only the undersurface of the object subject to washing is washed. At the time of washing, washing liquid (L) spreads over the entire length of the width direction (from the front side toward the back side of Fig. 1), and washes the object subject to washing (22). Therefore, the amount of washing liquid consumed is limited only to that used for removing the fine particles liberated from the washed object and floated within oscillation container (11) by overflowing washing liquid (L).

Document F4 relates to a method of wet processing electronic components using ozonated process fluids. The electronic components are contacted with a wetting solution, and contacted with an ozonated process fluid containing gaseous ozone. The contacting of the

electronic components with an ozonated process fluid is performed in the presence of a base.

It is respectfully requested that the documents listed on the attached form PTO-SB08 be considered and officially cited in the present application.

6/02/2010

Date

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Respectfully submitted,

  
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